

Publikationen

- (2020): Wafer composite and method for producing semiconductor components.
- (2020): Silicon carbide semiconductor device and a method for forming a silicon carbide semiconductor device.
- (2019): Method of manufacturing a semiconductor device having graphene material.
- (2019): Heißprägen von Glassubstraten als Basis kapazitiver Ultraschall-Sensorik. In: 2. Technologietag Angewandte Sensorik (TAS), Coburg.
- (2019): 4-Schiefspiegel-Teleskop: Justage und Stabilitätsaspekte. In: Untertitel, Deggendorf.
- (2019): Semiconductor devices and methods for forming semiconductor devices.
- (2019): Sensorik mit 2D-Materialien. In: Technologietag Angewandte Sensorik, Coburg.
- (2019): Semiconductor device including a heat sink structure.
- (2019): Method of manufacturing semiconductor devices by bonding a semiconductor disk on a base substrate, composite wafer and semiconductor device.
- (2019): Fahrzeugbeleuchtungsanordnung, Leuchtmitteltreiberschaltung und Verfahren zur Bereitstellung von Informationen zur Bestimmung eines Beleuchtungszustandes.
- (2019): Process for the formation of a graphene membrane component, graphene membrane component, microphone and Hall-effect sensor.
- (2019): Elektronisches Identifikationsdokument und Verfahren zur Herstellung eines elektronischen Identifikationsdokuments.
- (2019): Anomalieerkennung in industriellen Netzwerken - Cybersicherheit mit Machine Learning. In: Forum Künstliche Intelligenz, Stuttgart.
- (2019): Cybersicherheit in industriellen Netzwerken - Intrusion Detection mit Machine Learning. In: Forum Safety & Security, Sindelfingen.
- (2019): Secure per Machine Learning - Wie KI die Informationssicherheit verbessern kann. In: Computer & Automation (Sonderheft Safety & Security), no. Juni.
- (2019): Cybersicherheit in industriellen Netzwerken - Intrusion Detection mit Machine Learning. In: Digitaler Tagungsband zum Forum Safety & Security (8.- 10. Juli 2019, Sindelfingen).
- (2019): Entwicklung einer wasserdichten LED Flächenleuchte mit direkt im Glas eingebrachtem Konvertermaterial. Poster. In: DGaO Proceedings zur 120. Jahrestagung (11.-15.06.2019; Darmstadt).
- (2019): Schichtstruktur und Verfahren zur Herstellung einer Schichtstruktur.
- (2019): Hacking an optics manufacturing machine: You don't see it coming?!. In: Proceedings of SPIE 11171 (Sixth European Seminar on Precision Optics Manufacturing, 1117101 [9-10 April 2019, Teisnach]), Bellingham, WA, USA. DOI: 10.1117/12.2526691.
- (2019): Accurate Graphene-Metal Junction Characterization. In: IEEE Journal of the Electron Devices Society (J-EDS), vol. 7, pp. 219-226. DOI: 10.1109/JEDS.2019.2891516.

(2019): Photo-acoustic gas sensor module having light emitter and detector units.

(2019): Sensor arrangement for particle analysis and a method for particle analysis.

(2019): Elektronische Vorrichtung.

(2019): Development of a waterproof, high color fidelity LED Light Panel. In: 6th European Seminar on Precision Optics Manufacturing (POM19), Teisnach.

(2018): Abstandssensor.

(2018): Herstellung von planar integrierten Multimode-Wellenleitern in Glas für asymmetrische Verzweiger. In: DGaO-Proceedings 2018.

(2018): Simulation zur Herstellung von planar integrierten Multimode-Wellenleitern in Glas. In: DGaO-Proceedings 2018.

(2018): Distance sensor.

(2018): Process for the formation of a graphene membrane component, graphene membrane component, microphone and Hall-effect sensor.

(2018): Semiconductor device having a graphene layer, and method manufacturing thereof.

(2018): Sensor arrangement, battery cell and energy system.

(2018): Graphene gas sensor for measuring the concentration of carbon dioxide in gas environments.

(2018): Semiconductor device including a phase change material.

(2018): Method for processing a carrier and method for transferring a graphene layer.

(2018): Semiconductor package, smart card and method for producing a semiconductor package.

(2018): Verfahren zur Herstellung eines Grabenkondensators.

(2018): Glas als Verpackungsmaterial für Lebensmittel. Posterpräsentation. In: 5. Tag der Forschung, Deggendorf.

(2017): Method for processing a carrier.

(2017): Model based laser-ultrasound determination of hardness gradients of gas-carburized steel. In: NDT & E International, vol. 88, pp. 24-32. DOI: 10.1016/j.ndteint.2017.02.006.

(2017): Power semiconductor device including a cooling material.

(2017): Apparatus for determining a state of a rechargeable battery or of a battery, a rechargeable battery or a battery, and a method for determining a state of a rechargeable battery or of a battery.

(2017): Method of forming a graphene structure.

(2017): Hall effect sensor with graphene detection layer.

(2017): Two-dimensional material containing electronic components.

(2017): Method for manufacturing a composite wafer having a graphite core, and composite wafer having a graphite core.

(2017): Fluid sensor chip and method for manufacturing the same.

(2017): Method for making a sensor device using a graphene layer.



- (2017): Characterization methods for solid thermal interface materials. In: IEEE Transactions on Components, Packaging and Manufacturing Technology, vol. 8, no. 6, pp. 1024-1031. DOI: 10.1109/TCPMT.2017.2748238.
- (2017): The integration of graphene into microelectronic devices. In: Beilstein Journal of Nanotechnology, vol. 8, pp. 1056-1064. DOI: 10.3762/bjnano.8.107.
- (2017): Comparison of Supervised, Semi-supervised and Unsupervised Learning Methods in Network Intrusion Detection Systems (NIDS) Application. In: Anwendungen und Konzepte in der Wirtschaftsinformatik (AKWI), no. 6, pp. 10-19.
- (2016): Sensor unit.
- (2016): Messen mit seismischem Spürsinn. In: Jahresmagazin Mess- und Sensortechnik.
- (2016): Vergleich zwischen Laser-Doppler- und photorefraktivem Interferometer zur Messung von akustischen Oberflächenwellen unter industriellen Bedingungen. In: 18. GMA/ITG - Fachtagung Sensoren und Messsysteme 2016. DOI: 10.5162/sensoren2016/6.1.3.
- (2016): MEMS acoustic transducer, MEMS microphone, MEMS microspeaker, array of speakers and method for manufacturing an acoustic transducer.
- (2016): Temperature sensor.
- (2016): Electronic device.
- (2016): Method for processing a carrier and an electronic component.
- (2016): Composite wafer for bonding and encapsulation of a SiC-based functional layer.
- (2016): Fluid sensor chip and method for manufacturing the same.
- (2016): Electrical contact for graphene part.
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- (2016): Challenges in process integration of graphene for manufacturing microelectronic devices. eingeladener Vortrag. In: Graphene Week 2016, Warschau, Polen.
- (2016): Self-organized growth of graphene nanomesh with increased gas sensitivity. In: Nanoscale, vol. 8, no. 34, pp. 15490-15496.
- (2016): Simulations and measurements of annealed pyrolytic graphite-metal composite baseplates. In: IOP Conference Series:Materials Science and Engineering, vol. 118, no. Conference 1.
- (2016): Intrusion Detection Sensoren für industrielle Netzwerke. In: CYBICS - Cyber Security for Industrial Control Systems (Workshop & Konferenz für IT-Sicherheit in der Industrie), Würzburg.
- (2016): Schwachstellen, Angriffsszenarien und Schutzmaßnahmen bei industriellen Protokollen am Beispiel Profinet IO. In: Automation 2016 - Secure & reliable in the digital world, Baden-Baden.
- (2015): Stable vortex generation in liquid filled wells by mode conversion of surface acoustic waves. In: Physics Procedia, vol. 70, no. Proceedings of the 2015 ICU International Congress on Ultrasonics, Metz, France, pp. 98-101. DOI: 10.1016/j.phpro.2015.08.051.
- (2015): Method for manufacturing a composite wafer having a graphite core, and composite wafer having a graphite core.
- (2015): Compound structure and method for forming a compound structure.
- (2015): Sensor module and battery elements.



- (2015): Sensorbauelement und Verfahren.
- (2015): Semiconductor dies having opposite sides with different reflectivity.
- (2015): Sensor package and method of manufacturing thereof.
- (2015): Semiconductor device including a phase change material.
- (2015): Method for making a sensor device using a graphene layer.
- (2015): Going ballistic: Graphene hot electron transistors. In: Solid State Communications, vol. 224, no. December, pp. 64-75. DOI: 10.1016/j.ssc.2015.08.012.
- (2015): Residual Metallic Contamination of Transferred Chemical Vapor Deposited Graphene. In: ACS Nano, vol. 9, no. 5, pp. 4776-4785. DOI: 10.1021/acsnano.5b01261.
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- (2014): Fan-out-Element für Mehrkernfasern.
- (2014): Method for manufacturing a composite wafer having a graphite core, and composite wafer having a graphite core.
- (2014): Vehicle lighting arrangement.
- (2014): Method for making a sensor device using a graphene layer.
- (2014): Method of processing a contact pad, method of manufacturing a contact pad, and integrated circuit element.
- (2014): Integriertes Bauelement und Verfahren zur Trennung einer elektrisch leitfähigen Verbindung.
- (2014): Graphene - Balancing the Elephant. Eingeladener Vortrag. In: 6. NRW Nano-Konferenz, Dortmund.
- (2014): Perspectives of Graphene in Semiconductor Industry. eingeladener Vortrag. In: TNT 2014, Barcelona, Spanien.
- (2014): Perspective of ICT industry on the use of graphene. Eingeladener Vortrag. In: 6th Stuttgart NanoDays Workshop, Stuttgart.
- (2014): Graphene- Balancing the Elephant. Eingeladener Vortrag. In: IHP Institutsseminar, Frankfurt (Oder).
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- (2014): Cyber Security for Process Control Networks. In: 1st European Seminar on Precision Optics Manufacturing, Teisnach.
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- (2013): Enhanced Embedded Device Security by Combining Hardware-Based Trust Mechanisms. Poster-Session. In: ACM Conference on Computer and Communications Security, Berlin.
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